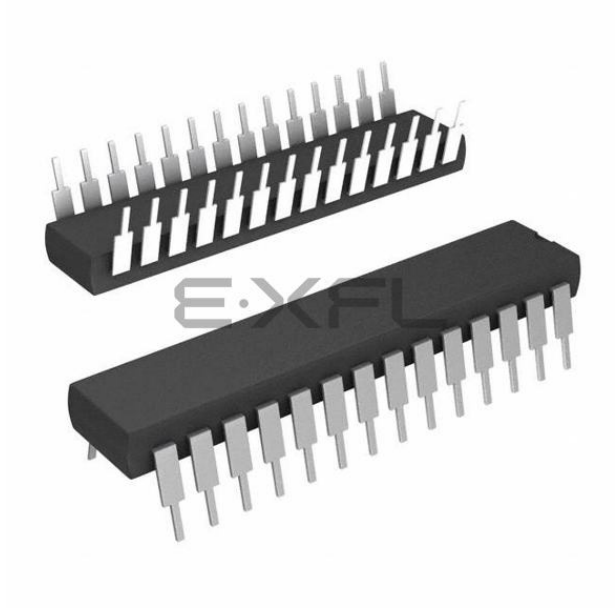

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Applications of "Embedded - Microcontrollers"

Details	
Product Status	Active
Core Processor	PIC
Core Size	8-Bit
Speed	25MHz
Connectivity	I²C, SPI, UART/USART
Peripherals	Brown-out Detect/Reset, HLVD, POR, PWM, WDT
Number of I/O	25
Program Memory Size	48KB (24K x 16)
Program Memory Type	FLASH
EEPROM Size	1K x 8
RAM Size	3.8K x 8
Voltage - Supply (Vcc/Vdd)	4.2V ~ 5.5V
Data Converters	A/D 10x10b
Oscillator Type	Internal
Operating Temperature	-40°C ~ 125°C (TA)
Mounting Type	Through Hole
Package / Case	28-DIP (0.300", 7.62mm)
Supplier Device Package	28-SPDIP
Purchase URL	https://www.e-xfl.com/product-detail/microchip-technology/pic18f2525-e-sp

2.4 RC Oscillator

For timing insensitive applications, the “RC” and “RCIO” device options offer additional cost savings. The actual oscillator frequency is a function of several factors:

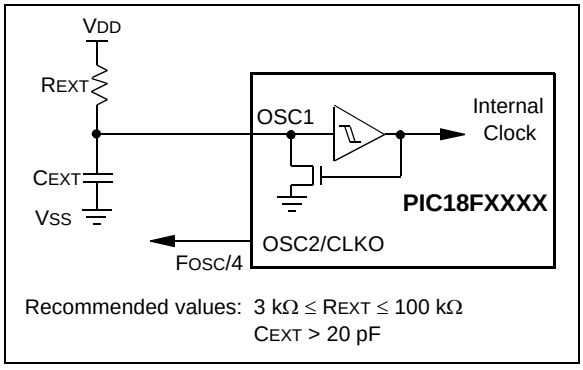
- supply voltage
- values of the external resistor (REXT) and capacitor (CEXT)
- operating temperature

Given the same device, operating voltage and temperature and component values, there will also be unit-to-unit frequency variations. These are due to factors such as:

- normal manufacturing variation
- difference in lead frame capacitance between package types (especially for low CEXT values)
- variations within the tolerance of limits of REXT and CEXT

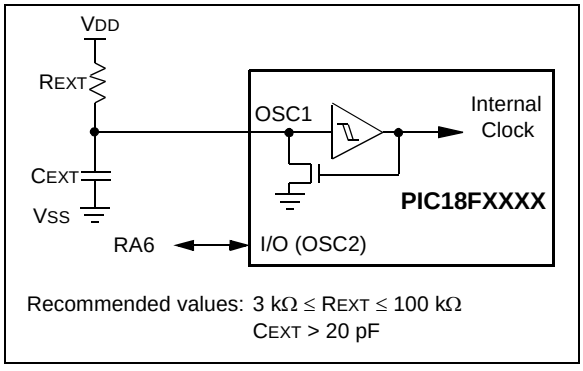
In the RC Oscillator mode, the oscillator frequency divided by 4 is available on the OSC2 pin. This signal may be used for test purposes or to synchronize other logic. Figure 2-5 shows how the R/C combination is connected.

FIGURE 2-5: RC OSCILLATOR MODE



The RCIO Oscillator mode (Figure 2-6) functions like the RC mode, except that the OSC2 pin becomes an additional general purpose I/O pin. The I/O pin becomes bit 6 of PORTA (RA6).

FIGURE 2-6: RCIO OSCILLATOR MODE



2.5 PLL Frequency Multiplier

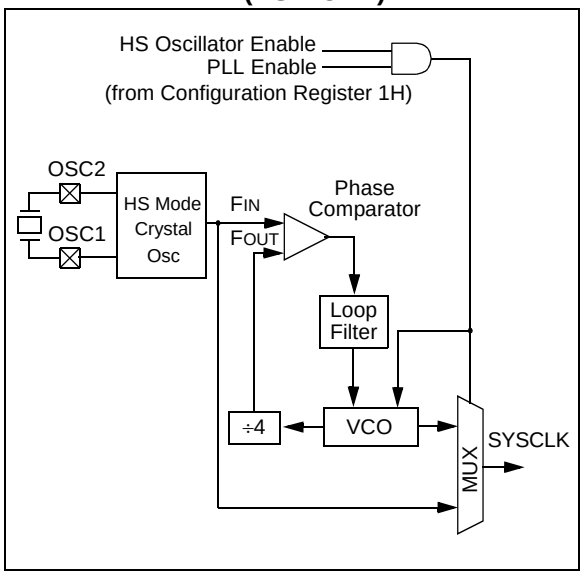
A Phase Locked Loop (PLL) circuit is provided as an option for users who wish to use a lower frequency oscillator circuit or to clock the device up to its highest rated frequency from a crystal oscillator. This may be useful for customers who are concerned with EMI due to high-frequency crystals or users who require higher clock speeds from an internal oscillator.

2.5.1 HSPLL OSCILLATOR MODE

The HSPLL mode makes use of the HS Oscillator mode for frequencies up to 10 MHz. A PLL then multiplies the oscillator output frequency by 4 to produce an internal clock frequency up to 40 MHz. The PLLEN bit is not available in this oscillator mode.

The PLL is only available to the crystal oscillator when the FOSC3:FOSC0 Configuration bits are programmed for HSPLL mode (= 0110).

FIGURE 2-7: PLL BLOCK DIAGRAM (HS MODE)



2.5.2 PLL AND INTOSC

The PLL is also available to the internal oscillator block in selected oscillator modes. In this configuration, the PLL is enabled in software and generates a clock output of up to 32 MHz. The operation of INTOSC with the PLL is described in **Section 2.6.4 “PLL in INTOSC Modes”**.

2.6 Internal Oscillator Block

The PIC18F2525/2620/4525/4620 devices include an internal oscillator block which generates two different clock signals; either can be used as the microcontroller's clock source. This may eliminate the need for external oscillator circuits on the OSC1 and/or OSC2 pins.

The main output (INTOSC) is an 8 MHz clock source, which can be used to directly drive the device clock. It also drives a postscaler, which can provide a range of clock frequencies from 31 kHz to 4 MHz. The INTOSC output is enabled when a clock frequency from 125 kHz to 8 MHz is selected.

The other clock source is the Internal RC oscillator (INTRC), which provides a nominal 31 kHz output. INTRC is enabled if it is selected as the device clock source; it is also enabled automatically when any of the following are enabled:

- Power-up Timer
- Fail-Safe Clock Monitor
- Watchdog Timer
- Two-Speed Start-up

These features are discussed in greater detail in **Section 23.0 "Special Features of the CPU"**.

The clock source frequency (INTOSC direct, INTRC direct or INTOSC postscaler) is selected by configuring the IRCF bits of the OSCCON register (page 30).

2.6.1 INTIO MODES

Using the internal oscillator as the clock source eliminates the need for up to two external oscillator pins, which can then be used for digital I/O. Two distinct configurations are available:

- In INTIO1 mode, the OSC2 pin outputs FOSC/4, while OSC1 functions as RA7 for digital input and output.
- In INTIO2 mode, OSC1 functions as RA7 and OSC2 functions as RA6, both for digital input and output.

2.6.2 INTOSC OUTPUT FREQUENCY

The internal oscillator block is calibrated at the factory to produce an INTOSC output frequency of 8.0 MHz.

The INTRC oscillator operates independently of the INTOSC source. Any changes in INTOSC across voltage and temperature are not necessarily reflected by changes in INTRC and vice versa.

2.6.3 OSCTUNE REGISTER

The internal oscillator's output has been calibrated at the factory but can be adjusted in the user's application. This is done by writing to the OSCTUNE register (Register 2-1). The tuning sensitivity is constant throughout the tuning range.

When the OSCTUNE register is modified, the INTOSC frequency will begin shifting to the new frequency. The INTRC clock will reach the new frequency within 8 clock cycles (approximately 8 * 32 μs = 256 μs). The INTOSC clock will stabilize within 1 ms. Code execution continues during this shift. There is no indication that the shift has occurred.

The OSCTUNE register also implements the INTSRC and PLLEN bits, which control certain features of the internal oscillator block. The INTSRC bit allows users to select which internal oscillator provides the clock source when the 31 kHz frequency option is selected. This is covered in greater detail in **Section 2.7.1 "Oscillator Control Register"**.

The PLLEN bit controls the operation of the frequency multiplier, PLL, in internal oscillator modes.

2.6.4 PLL IN INTOSC MODES

The 4x frequency multiplier can be used with the internal oscillator block to produce faster device clock speeds than are normally possible with an internal oscillator. When enabled, the PLL produces a clock speed of up to 32 MHz.

Unlike HSPLL mode, the PLL is controlled through software. The control bit, PLLEN (OSCTUNE<6>), is used to enable or disable its operation.

The PLL is available when the device is configured to use the internal oscillator block as its primary clock source (FOSC3:FOSC0 = 1001 or 1000). Additionally, the PLL will only function when the selected output frequency is either 4 MHz or 8 MHz (OSCCON<6:4> = 111 or 110). If both of these conditions are not met, the PLL is disabled.

The PLLEN control bit is only functional in those internal oscillator modes where the PLL is available. In all other modes, it is forced to '0' and is effectively unavailable.

2.6.5 INTOSC FREQUENCY DRIFT

The factory calibrates the internal oscillator block output (INTOSC) for 8 MHz. However, this frequency may drift as VDD or temperature changes, which can affect the controller operation in a variety of ways. It is possible to adjust the INTOSC frequency by modifying the value in the OSCTUNE register. This has no effect on the INTRC clock source frequency.

Tuning the INTOSC source requires knowing when to make the adjustment, in which direction it should be made, and in some cases, how large a change is needed. Three compensation techniques are discussed in **Section 2.6.5.1 "Compensating with the EUSART"**, **Section 2.6.5.2 "Compensating with the Timers"** and **Section 2.6.5.3 "Compensating with the CCP Module in Capture Mode"**, but other techniques may be used.

5.2 PIC18 Instruction Cycle

5.2.1 CLOCKING SCHEME

The microcontroller clock input, whether from an internal or external source, is internally divided by four to generate four non-overlapping quadrature clocks (Q1, Q2, Q3 and Q4). Internally, the program counter is incremented on every Q1; the instruction is fetched from the program memory and latched into the instruction register during Q4. The instruction is decoded and executed during the following Q1 through Q4. The clocks and instruction execution flow are shown in Figure 5-3.

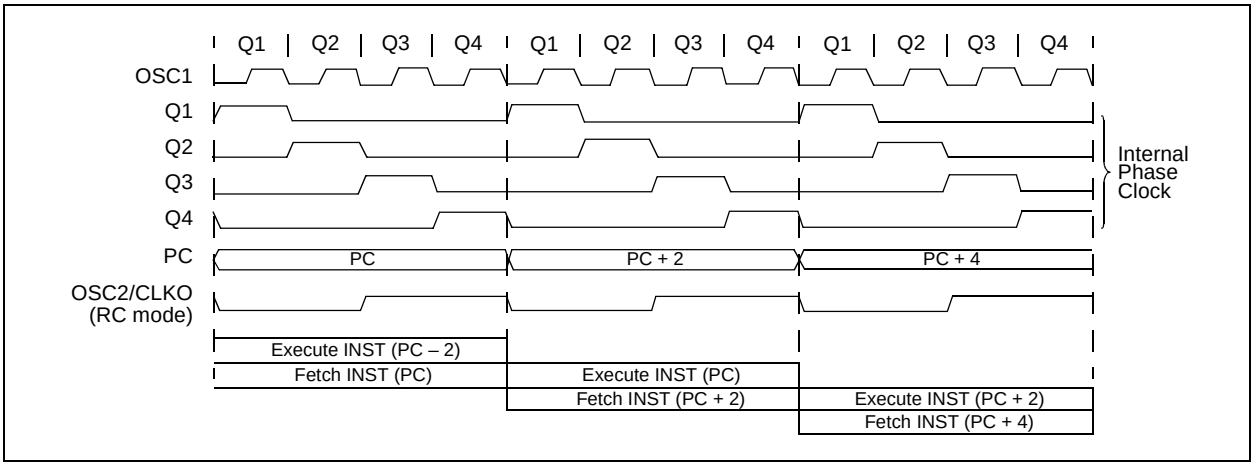
5.2.2 INSTRUCTION FLOW/PIPELINING

An “Instruction Cycle” consists of four Q cycles: Q1 through Q4. The instruction fetch and execute are pipelined in such a manner that a fetch takes one instruction cycle, while the decode and execute take another instruction cycle. However, due to the pipelining, each instruction effectively executes in one cycle. If an instruction causes the program counter to change (e.g., `GOTO`), then two cycles are required to complete the instruction (Example 5-3).

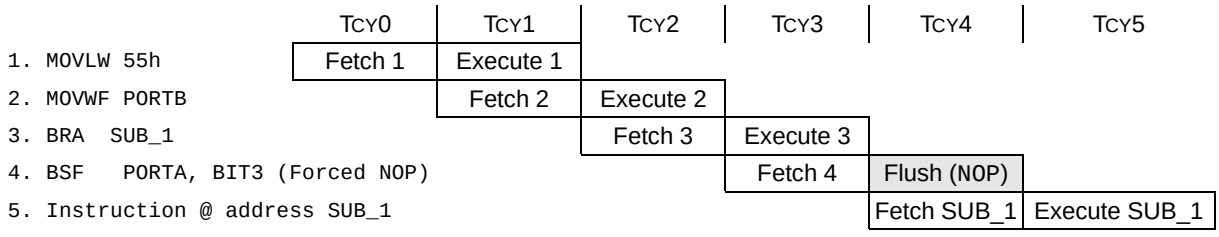
A fetch cycle begins with the Program Counter (PC) incrementing in Q1.

In the execution cycle, the fetched instruction is latched into the Instruction Register (IR) in cycle Q1. This instruction is then decoded and executed during the Q2, Q3 and Q4 cycles. Data memory is read during Q2 (operand read) and written during Q4 (destination write).

FIGURE 5-3: CLOCK/INSTRUCTION CYCLE



EXAMPLE 5-3: INSTRUCTION PIPELINE FLOW



All instructions are single cycle, except for any program branches. These take two cycles since the fetch instruction is “flushed” from the pipeline while the new instruction is being fetched and then executed.

5.3.5 STATUS REGISTER

The STATUS register, shown in Register 5-2, contains the arithmetic status of the ALU. As with any other SFR, it can be the operand for any instruction.

If the STATUS register is the destination for an instruction that affects the Z, DC, C, OV or N bits, the results of the instruction are not written; instead, the STATUS register is updated according to the instruction performed. Therefore, the result of an instruction with the STATUS register as its destination may be different than intended. As an example, `CLRF STATUS` will set the Z bit and leave the remaining Status bits unchanged (‘`000u u1uu`’).

It is recommended that only `BCF`, `BSF`, `SWAPF`, `MOVFF` and `MOVWF` instructions are used to alter the STATUS register, because these instructions do not affect the Z, C, DC, OV or N bits in the STATUS register.

For other instructions that do not affect Status bits, see the instruction set summaries in Table 24-2 and Table 24-3.

Note:	The C and DC bits operate as the $\overline{\text{borrow}}$ and digit $\overline{\text{borrow}}$ bits, respectively, in subtraction.

REGISTER 5-2: STATUS REGISTER

U-0	U-0	U-0	R/W-x	R/W-x	R/W-x	R/W-x	R/W-x
—	—	—	N	OV	Z	DC(1)	C(2)
bit 7							bit 0

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as ‘0’	
-n = Value at POR	‘1’ = Bit is set	‘0’ = Bit is cleared	x = Bit is unknown

bit 7-5 **Unimplemented:** Read as ‘0’

bit 4 **N:** Negative bit

This bit is used for signed arithmetic (2’s complement). It indicates whether the result was negative (ALU MSB = 1).

1 = Result was negative
0 = Result was positive

bit 3 **OV:** Overflow bit

This bit is used for signed arithmetic (2’s complement). It indicates an overflow of the 7-bit magnitude which causes the sign bit (bit 7) to change state.

1 = Overflow occurred for signed arithmetic (in this arithmetic operation)
0 = No overflow occurred

bit 2 **Z:** Zero bit

1 = The result of an arithmetic or logic operation is zero
0 = The result of an arithmetic or logic operation is not zero

bit 1 **DC:** Digit Carry/$\overline{\text{borrow}}$ bit(1)

For `ADDWF, ADDLW, SUBLW` and `SUBWF` instructions:

1 = A carry-out from the 4th low-order bit of the result occurred
0 = No carry-out from the 4th low-order bit of the result

bit 0 **C:** Carry/$\overline{\text{borrow}}$ bit(2)

For `ADDWF, ADDLW, SUBLW` and `SUBWF` instructions:

1 = A carry-out from the Most Significant bit of the result occurred
0 = No carry-out from the Most Significant bit of the result occurred

Note 1: For $\overline{\text{borrow}}$, the polarity is reversed. A subtraction is executed by adding the 2’s complement of the second operand. For rotate (`RRF, RLF`) instructions, this bit is loaded with either bit 4 or bit 3 of the source register.

2: For $\overline{\text{borrow}}$, the polarity is reversed. A subtraction is executed by adding the 2’s complement of the second operand. For rotate (`RRF, RLF`) instructions, this bit is loaded with either the high or low-order bit of the source register.

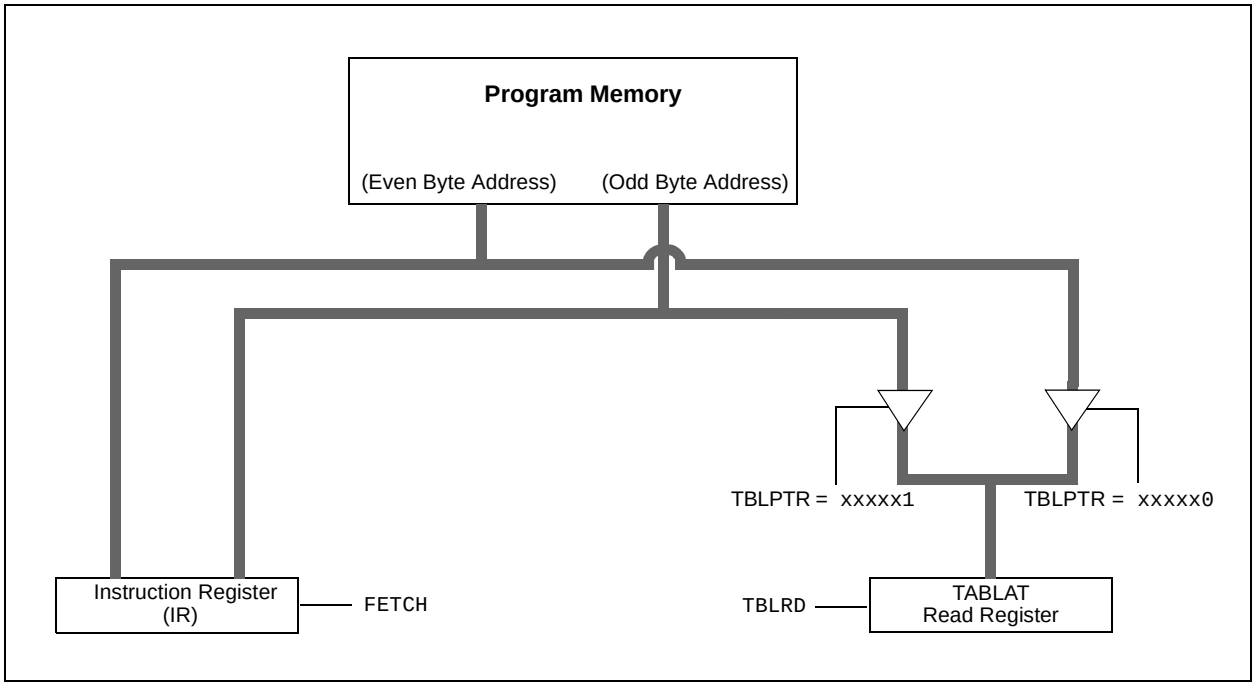
7.3 Reading the Flash Program Memory

The TBLRD instruction is used to retrieve data from program memory and places it into data RAM. Table reads from program memory are performed one byte at a time.

TBLPTR points to a byte address in program space. Executing TBLRD places the byte pointed to into TABLAT. In addition, TBLPTR can be modified automatically for the next table read operation.

The internal program memory is typically organized by words. The Least Significant bit of the address selects between the high and low bytes of the word. Figure 7-4 shows the interface between the internal program memory and the TABLAT.

FIGURE 7-4: READS FROM FLASH PROGRAM MEMORY



EXAMPLE 7-1: READING A FLASH PROGRAM MEMORY WORD

```
            MOVLW     CODE_ADDR_UPPER        ; Load TBLPTR with the base
            MOVWF     TBLPTRU                ; address of the word
            MOVLW     CODE_ADDR_HIGH
            MOVWF     TBLPTRH
            MOVLW     CODE_ADDR_LOW
            MOVWF     TBLPTRL
READ_WORD
            TBLRD*+                          ; read into TABLAT and increment
            MOVF      TABLAT, W              ; get data
            MOVWF     WORD_EVEN
            TBLRD*+                          ; read into TABLAT and increment
            MOVF      TABLAT, W              ; get data
            MOVWF     WORD_ODD
```

7.5 Writing to Flash Program Memory

The minimum programming block is 32 words or 64 bytes. Word or byte programming is not supported.

Table writes are used internally to load the holding registers needed to program the Flash memory. There are 64 holding registers used by the table writes for programming.

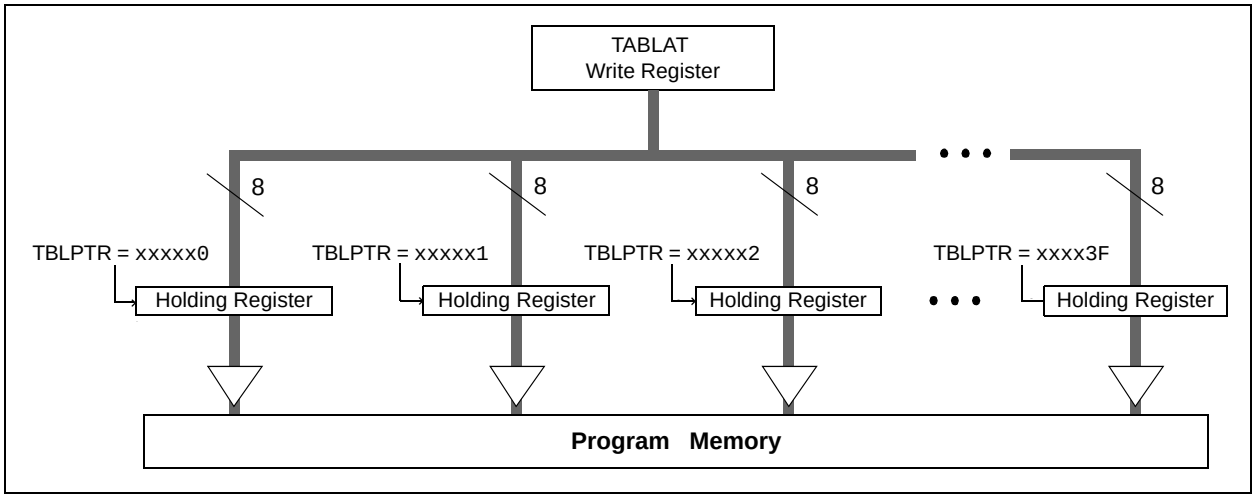
Since the Table Latch (TABLAT) is only a single byte, the TBLWT instruction may need to be executed 64 times for each programming operation. All of the table write operations will essentially be short writes because only the holding registers are written. At the end of updating the 64 holding registers, the EECON1 register must be written to in order to start the programming operation with a long write.

The long write is necessary for programming the internal Flash. Instruction execution is halted while in a long write cycle. The long write will be terminated by the internal programming timer.

The EEPROM on-chip timer controls the write time. The write/erase voltages are generated by an on-chip charge pump, rated to operate over the voltage range of the device.

Note:	The default value of the holding registers on device Resets and after write operations is FFh. A write of FFh to a holding register does not modify that byte. This means that individual bytes of program memory may be modified, provided that the change does not attempt to change any bit from a '0' to a '1'. When modifying individual bytes, it is not necessary to load all 64 holding registers before executing a write operation.

FIGURE 7-5: TABLE WRITES TO FLASH PROGRAM MEMORY



7.5.1 FLASH PROGRAM MEMORY WRITE SEQUENCE

The sequence of events for programming an internal program memory location should be:

1. Read 64 bytes into RAM.
2. Update data values in RAM as necessary.
3. Load Table Pointer register with address being erased.
4. Execute the row erase procedure.
5. Load Table Pointer register with address of first byte being written.
6. Write the 64 bytes into the holding registers with auto-increment.
7. Set the EECON1 register for the write operation:
   - set EEPGD bit to point to program memory;
   - clear the CFGS bit to access program memory;
   - set WREN to enable byte writes.
8. Disable interrupts.
9. Write 55h to EECON2.
10. Write 0AAh to EECON2.
11. Set the WR bit. This will begin the write cycle.
12. The CPU will stall for duration of the write (about 2 ms using internal timer).
13. Re-enable interrupts.
14. Verify the memory (table read).

This procedure will require about 6 ms to update one row of 64 bytes of memory. An example of the required code is given in Example 7-3.

Note:	Before setting the WR bit, the Table Pointer address needs to be within the intended address range of the 64 bytes in the holding register.

NOTES:

17.3.1 REGISTERS

The MSSP module has four registers for SPI mode operation. These are:

- MSSP Control Register 1 (SSPCON1)
- MSSP Status Register (SSPSTAT)
- Serial Receive/Transmit Buffer Register (SSPBUF)
- MSSP Shift Register (SSPSR) – Not directly accessible

SSPCON1 and SSPSTAT are the control and status registers in SPI mode operation. The SSPCON1 register is readable and writable. The lower 6 bits of the SSPSTAT are read-only. The upper two bits of the SSPSTAT are read/write.

SSPSR is the shift register used for shifting data in or out. SSPBUF is the buffer register to which data bytes are written to or read from.

In receive operations, SSPSR and SSPBUF together create a double-buffered receiver. When SSPSR receives a complete byte, it is transferred to SSPBUF and the SSPIF interrupt is set.

During transmission, the SSPBUF is not double-buffered. A write to SSPBUF will write to both SSPBUF and SSPSR.

REGISTER 17-1: SSPSTAT: MSSP STATUS REGISTER (SPI MODE)

R/W-0	R/W-0	R-0	R-0	R-0	R-0	R-0	R-0
SMP	CKE(1)	D/$\overline{A}$	P	S	R/$\overline{W}$	UA	BF
bit 7							bit 0

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as ‘0’	
-n = Value at POR	‘1’ = Bit is set	‘0’ = Bit is cleared	x = Bit is unknown

bit 7 **SMP:** Sample bit
SPI Master mode:
1 = Input data sampled at end of data output time
0 = Input data sampled at middle of data output time
SPI Slave mode:
SMP must be cleared when SPI is used in Slave mode.

bit 6 **CKE:** SPI Clock Select bit(1)
1 = Transmit occurs on transition from active to Idle clock state
0 = Transmit occurs on transition from Idle to active clock state

bit 5 **D/$\overline{A}$:** Data/$\overline{\text{Address}}$ bit
Used in I^2C mode only.

bit 4 **P:** Stop bit
Used in I^2C mode only. This bit is cleared when the MSSP module is disabled, SSPEN is cleared.

bit 3 **S:** Start bit
Used in I^2C mode only.

bit 2 **R/$\overline{W}$:** Read/$\overline{\text{Write}}$ Information bit
Used in I^2C mode only.

bit 1 **UA:** Update Address bit
Used in I^2C mode only.

bit 0 **BF:** Buffer Full Status bit (Receive mode only)
1 = Receive complete, SSPBUF is full
0 = Receive not complete, SSPBUF is empty

Note 1: Polarity of clock state is set by the CKP bit (SSPCON1<4>).

FIGURE 17-14: I²C™ SLAVE MODE TIMING WITH SEN = 1 (RECEPTION, 10-BIT ADDRESS)

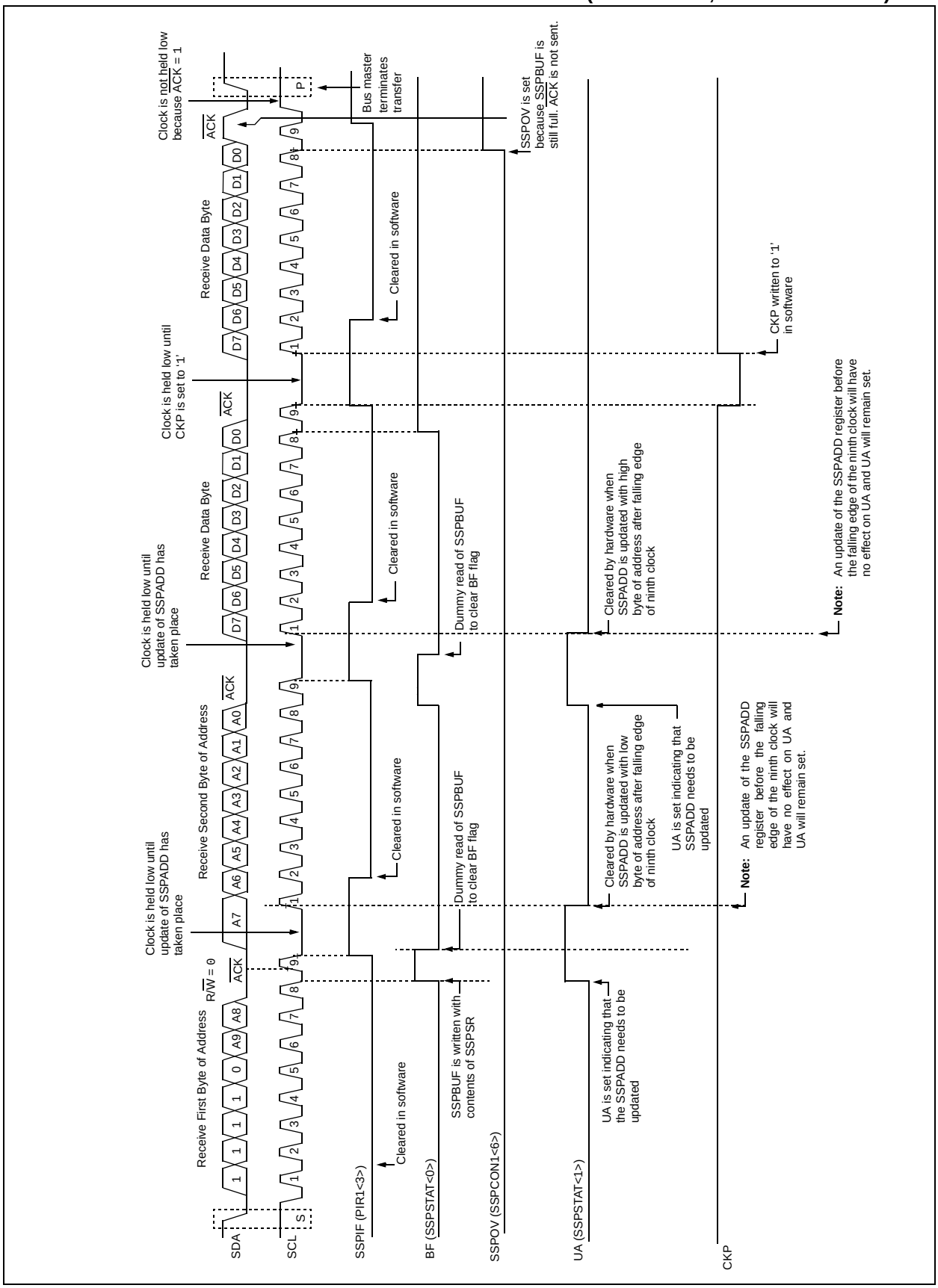


FIGURE 18-4: ASYNCHRONOUS TRANSMISSION

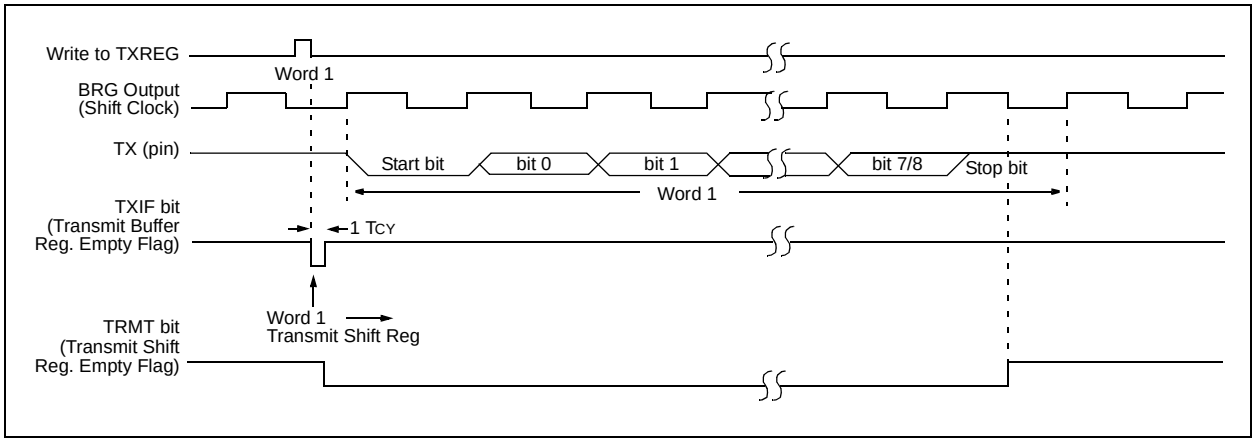
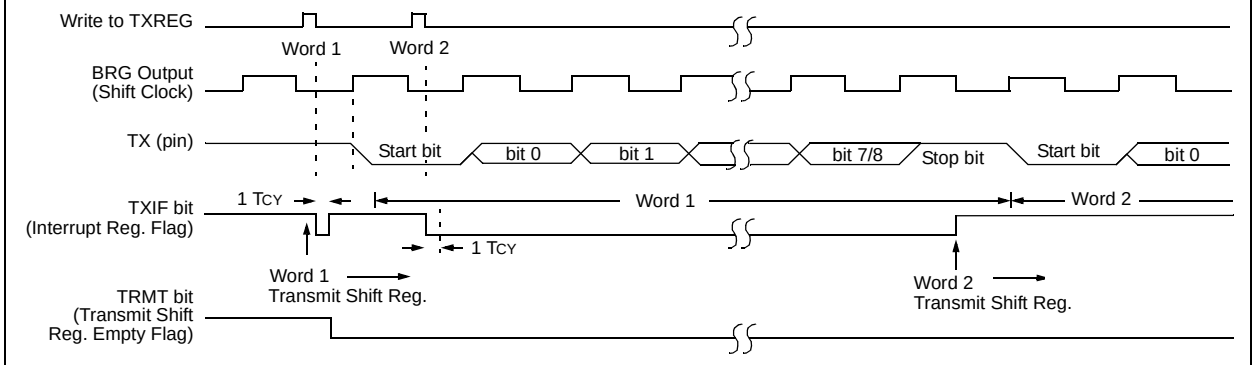


FIGURE 18-5: ASYNCHRONOUS TRANSMISSION (BACK TO BACK)



Note: This timing diagram shows two consecutive transmissions.

TABLE 18-5: REGISTERS ASSOCIATED WITH ASYNCHRONOUS TRANSMISSION

Name	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0	Reset Values on page
INTCON	GIE/GIEH	PEIE/GIEL	TMR0IE	INT0IE	RBIE	TMR0IF	INT0IF	RBIF	49
PIR1	PSPIF(1)	ADIF	RCIF	TXIF	SSPIF	CCP1IF	TMR2IF	TMR1IF	52
PIE1	PSPIE(1)	ADIE	RCIE	TXIE	SSPIE	CCP1IE	TMR2IE	TMR1IE	52
IPR1	PSPIP(1)	ADIP	RCIP	TXIP	SSPIP	CCP1IP	TMR2IP	TMR1IP	52
RCSTA	SPEN	RX9	SREN	CREN	ADDEN	FERR	OERR	RX9D	51
TXREG	EUSART Transmit Register								51
TXSTA	CSRC	TX9	TXEN	SYNC	SENDB	BRGH	TRMT	TX9D	51
BAUDCON	ABDOVF	RCIDL	RXDTP	TXCKP	BRG16	—	WUE	ABDEN	51
SPBRGH	EUSART Baud Rate Generator Register High Byte								51
SPBRG	EUSART Baud Rate Generator Register Low Byte								51

Legend: — = unimplemented locations read as '0'. Shaded cells are not used for asynchronous transmission.

Note 1: These bits are unimplemented on 28-pin devices and read as '0'.

19.1 A/D Acquisition Requirements

For the A/D converter to meet its specified accuracy, the charge holding capacitor (C_{HOLD}) must be allowed to fully charge to the input channel voltage level. The analog input model is shown in Figure 19-3. The source impedance (R_S) and the internal sampling switch (R_{SS}) impedance directly affect the time required to charge the capacitor C_{HOLD}. The sampling switch (R_{SS}) impedance varies over the device voltage (V_{DD}). The source impedance affects the offset voltage at the analog input (due to pin leakage current). **The maximum recommended impedance for analog sources is 2.5 kΩ.** After the analog input channel is selected (changed), the channel must be sampled for at least the minimum acquisition time before starting a conversion.

Note:	When the conversion is started, the holding capacitor is disconnected from the input pin.

To calculate the minimum acquisition time, Equation 19-1 may be used. This equation assumes that 1/2 LSb error is used (1024 steps for the A/D). The 1/2 LSb error is the maximum error allowed for the A/D to meet its specified resolution.

Example 19-3 shows the calculation of the minimum required acquisition time T_{ACQ}. This calculation is based on the following application system assumptions:

C_{HOLD}	=	25 pF
Rs	=	2.5 kΩ
Conversion Error	≤	1/2 LSb
V_{DD}	=	5V → Rss = 2 kΩ
Temperature	=	85°C (system max.)

EQUATION 19-1: ACQUISITION TIME

$$T_{ACQ} = \text{Amplifier Settling Time} + \text{Holding Capacitor Charging Time} + \text{Temperature Coefficient}$$
$$= T_{AMP} + T_C + T_{COFF}$$

EQUATION 19-2: A/D MINIMUM CHARGING TIME

$$V_{HOLD} = (V_{REF} - (V_{REF}/2048)) \bullet (1 - e^{(-T_C/C_{HOLD}(R_{IC} + R_{SS} + R_S))})$$
or
$$T_C = -(C_{HOLD})(R_{IC} + R_{SS} + R_S)\ln(1/2048)$$

EQUATION 19-3: CALCULATING THE MINIMUM REQUIRED ACQUISITION TIME

$T_{ACQ} = T_{AMP} + T_C + T_{COFF}$

$T_{AMP} = 0.2\ \mu s$

$T_{COFF} = (\text{Temp} - 25°C)(0.02\ \mu s/°C)$
$(85°C - 25°C)(0.02\ \mu s/°C)$
$1.2\ \mu s$

Temperature coefficient is only required for temperatures > 25°C. Below 25°C, T_{COFF} = 0 ms.

$T_C = -(C_{HOLD})(R_{IC} + R_{SS} + R_S)\ln(1/2047)$
$-(25\ pF)(1\ k\Omega + 2\ k\Omega + 2.5\ k\Omega)\ln(0.0004883)$
$1.05\ \mu s$

$T_{ACQ} = 0.2\ \mu s + 1\ \mu s + 1.2\ \mu s$
$2.4\ \mu s$

REGISTER 23-14: WDTCON: WATCHDOG TIMER CONTROL REGISTER

U-0	U-0	U-0	U-0	U-0	U-0	U-0	R/W-0
—	—	—	—	—	—	—	SWDTEN(1)
bit 7							bit 0

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'	
-n = Value at POR	'1' = Bit is set	'0' = Bit is cleared	x = Bit is unknown

bit 7-1 **Unimplemented**: Read as '0'

bit 0 **SWDTEN:** Software Controlled Watchdog Timer Enable bit(1)

1 = Watchdog Timer is on
0 = Watchdog Timer is off

Note 1: This bit has no effect if the Configuration bit, WDTEN, is enabled.

TABLE 23-2: SUMMARY OF WATCHDOG TIMER REGISTERS

Name	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0	Reset Values on page
RCON	IPEN	SBOREN(1)	—	$\overline{RI}$	$\overline{TO}$	$\overline{PD}$	$\overline{POR}$	$\overline{BOR}$	50
WDTCON	—	—	—	—	—	—	—	SWDTEN	50

Legend: — = unimplemented, read as '0'. Shaded cells are not used by the Watchdog Timer.

Note 1: The SBOREN bit is only available when the BOREN1:BOREN0 Configuration bits = 01; otherwise, it is disabled and reads as '0'. See **Section 4.4 "Brown-out Reset (BOR)"**.

POP **Pop Top of Return Stack**

Syntax: POP

Operands: None

Operation: (TOS) → bit bucket

Status Affected: None

Encoding:

0000	0000	0000	0110

Description: The TOS value is pulled off the return stack and is discarded. The TOS value then becomes the previous value that was pushed onto the return stack. This instruction is provided to enable the user to properly manage the return stack to incorporate a software stack.

Words: 1

Cycles: 1

Q Cycle Activity:

Q1	Q2	Q3	Q4
Decode	No operation	POP TOS value	No operation

Example:
```
POP
GOTO    NEW
```
Before Instruction
TOS = 0031A2h
Stack (1 level down) = 014332h

After Instruction
TOS = 014332h
PC = NEW

PUSH **Push Top of Return Stack**

Syntax: PUSH

Operands: None

Operation: (PC + 2) → TOS

Status Affected: None

Encoding:

0000	0000	0000	0101

Description: The PC + 2 is pushed onto the top of the return stack. The previous TOS value is pushed down on the stack. This instruction allows implementing a software stack by modifying TOS and then pushing it onto the return stack.

Words: 1

Cycles: 1

Q Cycle Activity:

Q1	Q2	Q3	Q4
Decode	PUSH PC + 2 onto return stack	No operation	No operation

Example:
```
PUSH
```
Before Instruction
TOS = 345Ah
PC = 0124h

After Instruction
PC = 0126h
TOS = 0126h
Stack (1 level down) = 345Ah

TSTFSZ **Test f, Skip if 0**

Syntax: TSTFSZ f {,a}

Operands: $0 \le f \le 255$
$a \in [0,1]$

Operation: skip if f = 0

Status Affected: None

Encoding:

0110	011a	ffff	ffff

Description: If 'f' = 0, the next instruction fetched during the current instruction execution is discarded and a NOP is executed, making this a two-cycle instruction.
If 'a' is '0', the Access Bank is selected.
If 'a' is '1', the BSR is used to select the GPR bank.
If 'a' is '0' and the extended instruction set is enabled, this instruction operates in Indexed Literal Offset Addressing mode whenever $f \le 95$ (5Fh). See **Section 24.2.3 "Byte-Oriented and Bit-Oriented Instructions in Indexed Literal Offset Mode"** for details.

Words: 1

Cycles: 1(2)
Note: 3 cycles if skip and followed by a 2-word instruction.

Q Cycle Activity:

Q1	Q2	Q3	Q4
Decode	Read register 'f'	Process Data	No operation

If skip:

Q1	Q2	Q3	Q4
No operation	No operation	No operation	No operation

If skip and followed by 2-word instruction:

Q1	Q2	Q3	Q4
No operation	No operation	No operation	No operation
No operation	No operation	No operation	No operation

Example:
```
HERE    TSTFSZ  CNT, 1
NZERO   :
ZERO    :
```
Before Instruction
PC = Address (HERE)
After Instruction
If CNT = 00h,
PC = Address (ZERO)
If CNT ≠ 00h,
PC = Address (NZERO)

XORLW **Exclusive OR Literal with W**

Syntax: XORLW k

Operands: $0 \le k \le 255$

Operation: (W) .XOR. k → W

Status Affected: N, Z

Encoding:

0000	1010	kkkk	kkkk

Description: The contents of W are XORed with the 8-bit literal 'k'. The result is placed in W.

Words: 1

Cycles: 1

Q Cycle Activity:

Q1	Q2	Q3	Q4
Decode	Read literal 'k'	Process Data	Write to W

Example:
```
XORLW   0AFh
```
Before Instruction
W = B5h
After Instruction
W = 1Ah

XORWF **Exclusive OR W with f**

Syntax: XORWF f {,d {,a}}

Operands: $0 \le f \le 255$
$d \in [0,1]$
$a \in [0,1]$

Operation: (W) .XOR. (f) → dest

Status Affected: N, Z

Encoding:

0001	10da	ffff	ffff

Description: Exclusive OR the contents of W with register 'f'. If 'd' is '0', the result is stored in W. If 'd' is '1', the result is stored back in the register 'f' (default).
If 'a' is '0', the Access Bank is selected. If 'a' is '1', the BSR is used to select the GPR bank.
If 'a' is '0' and the extended instruction set is enabled, this instruction operates in Indexed Literal Offset Addressing mode whenever $f \le 95$ (5Fh). See **Section 24.2.3 "Byte-Oriented and Bit-Oriented Instructions in Indexed Literal Offset Mode"** for details.

Words: 1

Cycles: 1

Q Cycle Activity:

Q1	Q2	Q3	Q4
Decode	Read register 'f'	Process Data	Write to destination

Example: `XORWF REG, 1, 0`

Before Instruction
REG = AFh
W = B5h
After Instruction
REG = 1Ah
W = B5h

26.2 DC Characteristics: Power-Down and Supply Current PIC18F2525/2620/4525/4620 (Industrial) PIC18LF2525/2620/4525/4620 (Industrial)

PIC18LF2525/2620/4525/4620 (Industrial)		**Standard Operating Conditions (unless otherwise stated)** Operating temperature -40°C ≤ TA ≤ +85°C for industrial				
PIC18F2525/2620/4525/4620 (Industrial, Extended)		**Standard Operating Conditions (unless otherwise stated)** Operating temperature -40°C ≤ TA ≤ +85°C for industrial -40°C ≤ TA ≤ +125°C for extended				
Param No.	**Device**	**Typ**	**Max**	**Units**	**Conditions**	
	Power-Down Current (IPD)(1)					
	PIC18LFX525/X620	0.1	0.5	µA	-40°C	VDD = 2.0V (**Sleep** mode)
		0.1	0.5	µA	+25°C	
		0.2	2.5	µA	+85°C	
	PIC18LFX525/X620	0.1	0.7	µA	-40°C	VDD = 3.0V (**Sleep** mode)
		0.1	0.7	µA	+25°C	
		0.3	3.5	µA	+85°C	
	All devices	0.1	1.0	µA	-40°C	VDD = 5.0V (**Sleep** mode)
		0.2	1.0	µA	+25°C	
		0.7	10	µA	+85°C	
	Extended devices only	10	100	µA	+125°C	

Legend: Shading of rows is to assist in readability of the table.

Note 1: The power-down current in Sleep mode does not depend on the oscillator type. Power-down current is measured with the part in Sleep mode, with all I/O pins in high-impedance state and tied to VDD or VSS and all features that add delta current disabled (such as WDT, Timer1 Oscillator, BOR, etc.).

2: The supply current is mainly a function of operating voltage, frequency and mode. Other factors, such as I/O pin loading and switching rate, oscillator type and circuit, internal code execution pattern and temperature, also have an impact on the current consumption.

The test conditions for all IDD measurements in active operation mode are:

OSC1 = external square wave, from rail-to-rail; all I/O pins tri-stated, pulled to VDD or VSS;

$\overline{MCLR}$ = VDD; WDT enabled/disabled as specified.

3: When operation below -10°C is expected, use T1OSC High-Power mode, where LPT1OSC (CONFIG3H<2>) = 0. When operation will always be above -10°C, then the low-power Timer1 oscillator may be selected.

4: BOR and HLVD enable internal band gap reference. With both modules enabled, current consumption will be less than the sum of both specifications.

26.2 DC Characteristics: Power-Down and Supply Current PIC18F2525/2620/4525/4620 (Industrial) PIC18LF2525/2620/4525/4620 (Industrial) (Continued)

PIC18LF2525/2620/4525/4620 (Industrial)		**Standard Operating Conditions (unless otherwise stated)** Operating temperature -40°C ≤ TA ≤ +85°C for industrial					
PIC18F2525/2620/4525/4620 (Industrial, Extended)		**Standard Operating Conditions (unless otherwise stated)** Operating temperature -40°C ≤ TA ≤ +85°C for industrial -40°C ≤ TA ≤ +125°C for extended					
Param No.	**Device**	**Typ**	**Max**	**Units**	**Conditions**		
	Module Differential Currents (ΔIWDT, ΔIBOR, ΔILVD, ΔIOSCB, ΔIAD)						
D026 (ΔIAD)	**A/D Converter**	0.2	1.0	µA	-40°C to +85°C	VDD = 2.0V	A/D on, not converting
		0.2	1.0	µA	-40°C to +85°C	VDD = 3.0V	
		0.2	1.0	µA	-40°C to +85°C	VDD = 5.0V	
		0.5	4.0	µA	-40°C to +125°C		
D022 (ΔIWDT)	**Watchdog Timer**	1.3	2.2	µA	-40°C	VDD = 2.0V	
		1.4	2.2	µA	+25°C		
		1.6	2.3	µA	+85°C		
		1.9	3.5	µA	-40°C	VDD = 3.0V	
		2.0	3.5	µA	+25°C		
		2.2	3.5	µA	+85°C		
		3.0	7.5	µA	-40°C	VDD = 5.0V	
		3.5	7.5	µA	+25°C		
		3.5	7.8	µA	+85°C		
		4.0	10	µA	+125°C		
D022A (ΔIBOR)	**Brown-out Reset(4)**	35	50	µA	-40°C to +85°C	VDD = 3.0V	
		40	55	µA	-40°C to +85°C	VDD = 5.0V	
		55	65	µA	-40°C to +125°C		
		0	2	µA	-40°C to +85°C		Sleep mode, BOREN1:BOREN0 = 10
		0	5	µA	-40°C to +125°C		
D022B (ΔILVD)	**High/Low-Voltage Detect(4)**	22	38	µA	-40°C to +85°C	VDD = 2.0V	
		25	40	µA	-40°C to +85°C	VDD = 3.0V	
		29	45	µA	-40°C to +85°C	VDD = 5.0V	
		30	45	µA	-40°C to +125°C		

Legend: Shading of rows is to assist in readability of the table.

Note 1: The power-down current in Sleep mode does not depend on the oscillator type. Power-down current is measured with the part in Sleep mode, with all I/O pins in high-impedance state and tied to VDD or VSS and all features that add delta current disabled (such as WDT, Timer1 Oscillator, BOR, etc.).

2: The supply current is mainly a function of operating voltage, frequency and mode. Other factors, such as I/O pin loading and switching rate, oscillator type and circuit, internal code execution pattern and temperature, also have an impact on the current consumption.

The test conditions for all IDD measurements in active operation mode are:

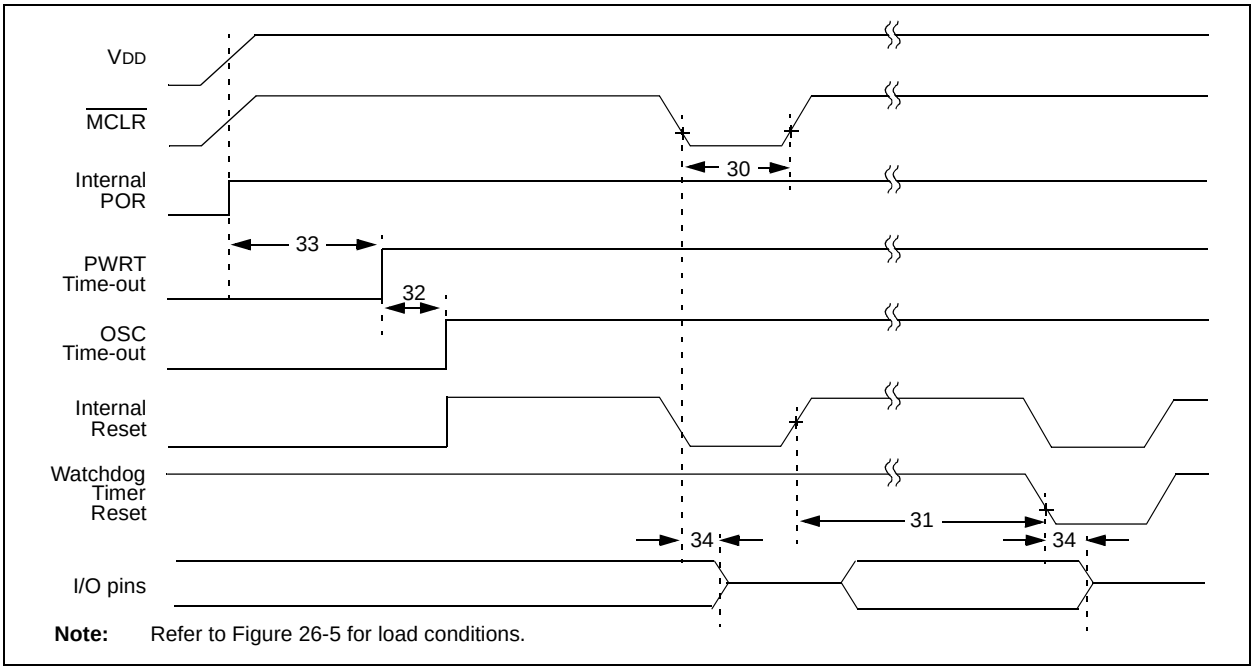
OSC1 = external square wave, from rail-to-rail; all I/O pins tri-stated, pulled to VDD or VSS;

$\overline{MCLR}$ = VDD; WDT enabled/disabled as specified.

3: When operation below -10°C is expected, use T1OSC High-Power mode, where LPT1OSC (CONFIG3H<2>) = 0. When operation will always be above -10°C, then the low-power Timer1 oscillator may be selected.

4: BOR and HLVD enable internal band gap reference. With both modules enabled, current consumption will be less than the sum of both specifications.

FIGURE 26-8: RESET, WATCHDOG TIMER, OSCILLATOR START-UP TIMER AND POWER-UP TIMER TIMING



Note: Refer to Figure 26-5 for load conditions.

FIGURE 26-9: BROWN-OUT RESET TIMING

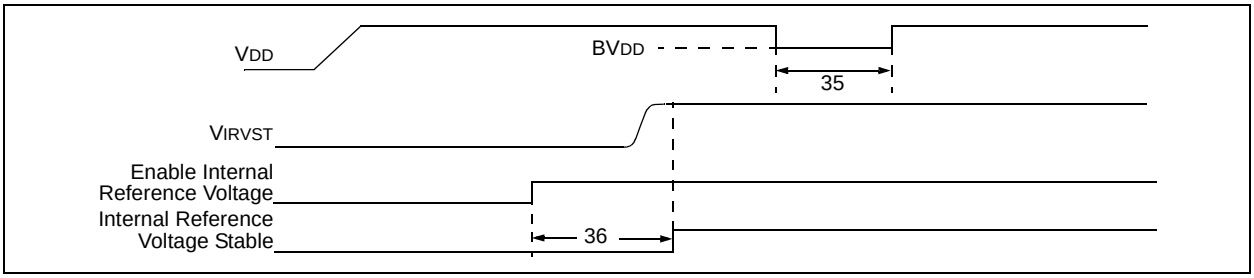


TABLE 26-10: RESET, WATCHDOG TIMER, OSCILLATOR START-UP TIMER, POWER-UP TIMER AND BROWN-OUT RESET REQUIREMENTS

Param. No.	Symbol	Characteristic	Min	Typ	Max	Units	Conditions
30	TmcL	$\overline{MCLR}$ Pulse Width (low)	2	—	—	µs	
31	TWDT	Watchdog Timer Time-out Period (no postscaler)	3.4	4.1	4.71	ms	
32	TOST	Oscillation Start-up Timer Period	1024 TOSC	—	1024 TOSC	—	TOSC = OSC1 period
33	TPWRT	Power-up Timer Period	55.6	65.5	75.4	ms	
34	TIOZ	I/O High-Impedance from $\overline{MCLR}$ Low or Watchdog Timer Reset	—	2	—	µs	
35	TBOR	Brown-out Reset Pulse Width	200	—	—	µs	VDD ≤ BVDD (see D005)
36	TIVRST	Time for Internal Reference Voltage to become Stable	—	20	50	µs	
37	TLVD	High/Low-Voltage Detect Pulse Width	200	—	—	µs	VDD ≤ VLVD
38	TCSD	CPU Start-up Time	—	10	—	µs	
39	TIOBST	Time for INTOSC to Stabilize	—	1	—	µs	

TABLE 26-19: I²C™ BUS DATA REQUIREMENTS (SLAVE MODE)

Param. No.	Symbol	Characteristic		Min	Max	Units	Conditions
100	THIGH	Clock High Time	100 kHz mode	4.0	—	µs	
			400 kHz mode	0.6	—	µs	
			MSSP module	1.5 TCY	—		
101	TLOW	Clock Low Time	100 kHz mode	4.7	—	µs	
			400 kHz mode	1.3	—	µs	
			MSSP module	1.5 TCY	—		
102	TR	SDA and SCL Rise Time	100 kHz mode	—	1000	ns	
			400 kHz mode	20 + 0.1 CB	300	ns	CB is specified to be from 10 to 400 pF
103	TF	SDA and SCL Fall Time	100 kHz mode	—	300	ns	
			400 kHz mode	20 + 0.1 CB	300	ns	CB is specified to be from 10 to 400 pF
90	TSU:STA	Start Condition Setup Time	100 kHz mode	4.7	—	µs	Only relevant for Repeated Start condition
			400 kHz mode	0.6	—	µs	
91	THD:STA	Start Condition Hold Time	100 kHz mode	4.0	—	µs	After this period, the first clock pulse is generated
			400 kHz mode	0.6	—	µs	
106	THD:DAT	Data Input Hold Time	100 kHz mode	0	—	ns	
			400 kHz mode	0	0.9	µs	
107	TSU:DAT	Data Input Setup Time	100 kHz mode	250	—	ns	**(Note 2)**
			400 kHz mode	100	—	ns	
92	TSU:STO	Stop Condition Setup Time	100 kHz mode	4.7	—	µs	
			400 kHz mode	0.6	—	µs	
109	TAA	Output Valid from Clock	100 kHz mode	—	3500	ns	**(Note 1)**
			400 kHz mode	—	—	ns	
110	TBUF	Bus Free Time	100 kHz mode	4.7	—	µs	Time the bus must be free before a new transmission can start
			400 kHz mode	1.3	—	µs	
D102	CB	Bus Capacitive Loading		—	400	pF	

Note 1: As a transmitter, the device must provide this internal minimum delay time to bridge the undefined region (min. 300 ns) of the falling edge of SCL to avoid unintended generation of Start or Stop conditions.

2: A Fast mode I²C bus device can be used in a Standard mode I²C bus system, but the requirement TSU:DAT ≥ 250 ns must then be met. This will automatically be the case if the device does not stretch the LOW period of the SCL signal. If such a device does stretch the LOW period of the SCL signal, it must output the next data bit to the SDA line, TR max. + TSU:DAT = 1000 + 250 = 1250 ns (according to the Standard mode I²C bus specification), before the SCL line is released.

FIGURE 27-13: TYPICAL AND MAXIMUM IDD ACROSS VDD (RC_RUN MODE, 31 kHz)

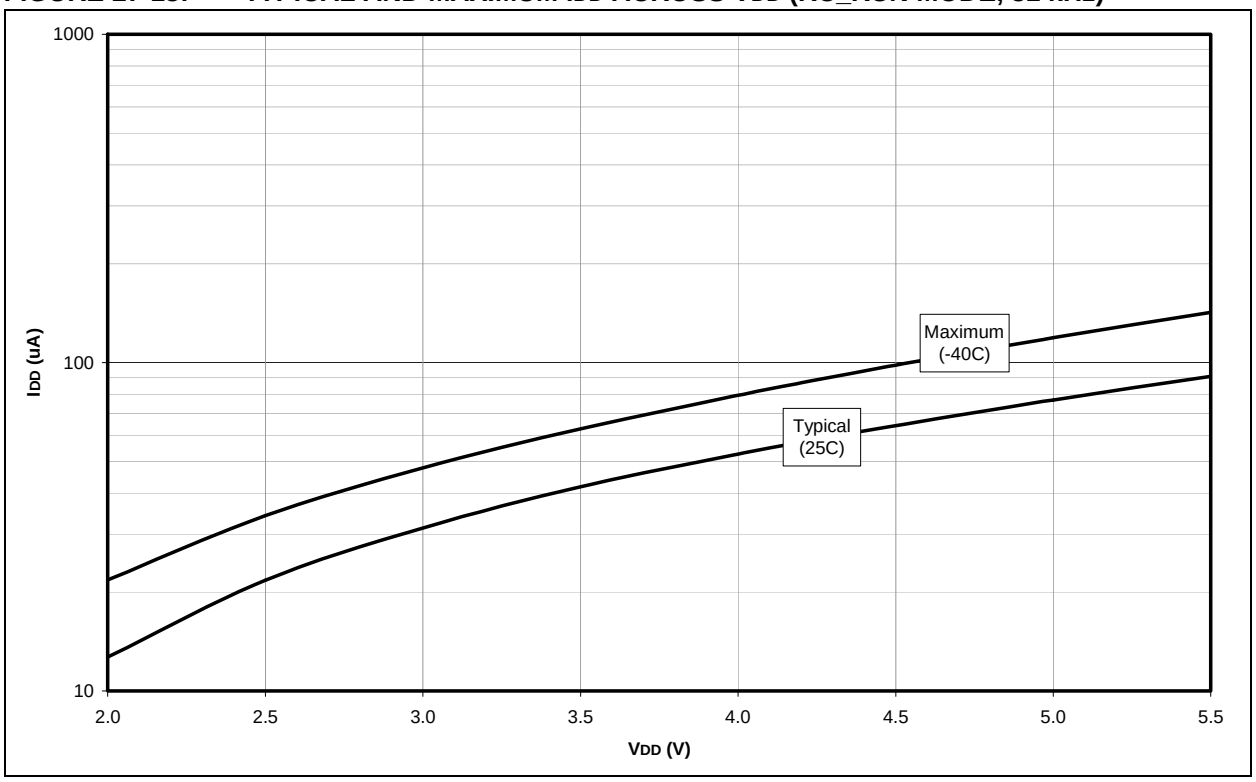


FIGURE 27-14: TYPICAL IDD ACROSS VDD (RC_IDLE MODE, 25°C)